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Thermosense: Thermal Infrared Applications XXXIV

**Douglas Burleigh
Gregory R. Stockton**
Editors

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Contents

vii	Conference Committee
ix	Introduction

SESSION 1 NONDESTRUCTIVE TESTING (NDT) I

- 8354 03 **Thermography inspection for early detection of composite damage in structures during fatigue loading** [8354-02]
J. N. Zalameda, E. R. Burke, F. R. Parker, NASA Langley Research Ctr. (United States); J. P. Seebo, Lockheed Martin Corp. (United States); C. W. Wright, NASA Langley Research Ctr. (United States); J. B. Bly, Lockheed Martin Corp. (United States)
- 8354 05 **Water ingress detection in honeycomb sandwich panels by passive infrared thermography using a high-resolution thermal imaging camera** [8354-04]
C. Ibarra-Castanedo, Univ. Laval (Canada); L. Brault, F. Marcotte, Telops (Canada); M. Genest, National Research Council Canada (Canada); V. Farley, Telops (Canada); X. Maldague, Univ. Laval (Canada)
- 8354 06 **Inspection of composite structures using line scanning thermography** [8354-05]
O. Ley, M. Butera, V. Godinez, Mistras Group (United States)
- 8354 08 **Matched excitation for thermal nondestructive testing of carbon fiber reinforced plastic materials** [8354-07]
R. Mulaveesala, Indian Institute of Technology Ropar (India); G. V. Subbarao, KL Univ. (India); M. Amarnath, PDPM Indian Institute of Information Technology, Design & Manufacturing Jabalpur (India)
- 8354 09 **Detecting corrosion in thick metals by applying active IR thermography** [8354-08]
V. P. Vavilov, A. O. Chulkov, Tomsk Polytechnic Univ. (Russian Federation)
- 8354 0A **Development of nondestructive crack inspection technique for conveyance roll using vibro-thermography** [8354-09]
D. Imanishi, Y. Nishina, Y. Yoshinaga, JFE Steel Corp. (Japan)
- 8354 0B **Nondestructive evaluation of concrete structures by nonstationary thermal wave imaging** [8354-10]
R. Mulaveesala, Indian Institute of Technology Ropar (India); S. S. B. Panda, R. N. Mude, M. Amarnath, PDPM Indian Institute of Information Technology, Design & Manufacturing Jabalpur (India)

SESSION 2 NONDESTRUCTIVE TESTING (NDT) II

- 8354 0C **Thermal wave imaging techniques for inspection of plywood materials** [8354-11]
R. Mulaveesala, Indian Institute of Technology Ropar (India); V. N. P., D. Ravi, M. Amarnath, PDPM Indian Institute of Information Technology, Design & Manufacturing Jabalpur (India)

- 8354 0D **C/C composite brake disk nondestructive evaluation by IR thermography** [8354-12]
T. P. Chu, A. Poudel, P. Filip, Southern Illinois Univ. Carbondale (United States)
- 8354 0E **Thermal measurement of brake pad lining surfaces during the braking process** [8354-13]
T. Piątkowski, H. Polakowski, M. Kastek, P. Baranowski, K. Damaziak, J. Małachowski,
Ł. Mazurkiewicz, Military Univ. of Technology (Poland)

SESSION 3 AEROSPACE

- 8354 0F **Thermographic imaging of the space shuttle during re-entry using a near-infrared sensor** [8354-14]
J. N. Zalameda, T. J. Horvath, R. V. Kerns, E. R. Burke, NASA Langley Research Ctr. (United States); J. C. Taylor, T. Spisz, D. M. Gibson, The Johns Hopkins Univ. Applied Physics Lab. (United States); E. J. Shea, Futron Corp. (United States); C. D. Mercer, SGT, Inc. (United States); R. J. Schwartz, AMA, Inc. (United States); S. Tack, Naval Air Warfare Ctr. Weapons Div. (United States); B. C. Bush, Photon Research Associates Inc. (United States); R. F. Dantowitz, M. J. Kozubal, Celestial Computing, Inc. (United States)
- 8354 0G **Processing ground-based near-infrared imagery of space shuttle re-entries** [8354-15]
T. S. Spisz, J. C. Taylor, S. W. Kennerly, K. Osei-Wusu, D. M. Gibson, The Johns Hopkins Univ. Applied Physics Lab. (United States); T. J. Horvath, J. N. Zalameda, R. V. Kerns, NASA Langley Research Ctr. (United States); E. J. Shea, Futron Corp. (United States); C. D. Mercer, SGT, Inc. (United States); R. J. Schwartz, AMA, Inc. (United States); R. F. Dantowitz, M. J. Kozubal, Celestial Computing, Inc. (United States)
- 8354 0H **Spatially resolved infrared spectra of F109 turbofan exhaust** [8354-16]
J. L. Harley, Air Force Institute of Technology (United States); A. J. Rolling, C. F. Wisniewski, U.S. Air Force Academy (United States); K. C. Gross, Air Force Institute of Technology (United States)

SESSION 4 BUILDINGS

- 8354 0I **High-resolution texturing of building facades with thermal images** [8354-17]
M. Scaioni, Tongji Univ. (China); E. Rosina, L. Barazzetti, M. Previtali, V. Redaelli, Politecnico di Milano (Italy)
- 8354 0J **An evaluation of the impact of an example of thermal bridging in buildings and a design alternative** [8354-18]
J. M. Kleinfeld, Kleinfeld Technical Services, Inc. (United States)
- 8354 0K **Building thermography and energy performance directive of buildings** [8354-19]
T. Kauppinen, VTT Technologies and Services for Buildings (Finland); S. Siikanen, VTT Optical Measurement Technologies (Finland)

SESSION 5 INDUSTRIAL APPLICATIONS

- 8354 0L **Monitoring and thermal effects of relubrication of greased bearings** [8354-20]
R. N. Wurzbach, E. W. Bupp, L. A. Williams, MRG Labs. (United States)

- 8354 0M **In-line particle measurement in a recovery boiler using high-speed infrared imaging** [8354-21]
S. Siikanen, VTT Technical Research Ctr. of Finland (Finland); P. Miikkulainen, Andritz Oy (Finland); M. Kaarre, M. Juuti, VTT Technical Research Ctr. of Finland (Finland)
- 8354 0N **Thermographic evaluation of hydrogenerator losses** [8354-22]
E. da Costa Bortoni, Univ. Federal de Itajubá (Brazil); R. Teixeira Siniscalchi, Eletrobras Furnas (Brazil)
- 8354 0O **Opportunities and challenges of the application of dynamic, multispectral thermography as a means of improving the effectiveness of furnace processes in the petrochemical industry** [8354-23]
P. Pregowski, Pregowski Infrared Services (Poland); G. Goleniewski, W. Komosa, A. Korytkowski, PKN ORLEN S.A. (Poland)
- 8354 0P **Infrared evaluation of insulated pipelines to detect water that could cause Corrosion Under Insulation (CUI)** [8354-24]
D. Burleigh, La Jolla Cove Consulting (United States); H. A. Sanders, Kakivik Asset Management, LLC (United States)
- 8354 0Q **Sportswear textiles emissivity measurement: comparison of IR thermography and emissometry techniques** [8354-25]
P. Bison, E. Grinzato, CNR-ITC (Italy); A. Libbra, A. Muscio, EELab. (Italy)

SESSION 6 SECURITY AND SURVEILLANCE

- 8354 0S **Achieving thermography with a thermal security camera using uncooled amorphous silicon microbolometer image sensors** [8354-28]
Y.-W. Wang, C. Tesdahl, J. Owens, D. Dorn, Schneider Electric (United States)
- 8354 0T **Using aerial infrared thermography to detect utility theft of service** [8354-29]
G. R. Stockton, R. G. Lucas, RecoverIR, Inc. (United States)

SESSION 7 BIOLOGICAL APPLICATIONS

- 8354 0U **Development and validation of experimental models for hyperemic thermal response using IR imaging** [8354-30]
E. Moreno, Boston Univ. (United States); S.-J. Hsieh, B. G. Palomares, Texas A&M Univ. (United States)
- 8354 0V **Breast cancer in tough economic times: disruptive technology emerging (Invited Paper)** [8354-31]
P. Bretz, Desert Breast and Osteoporosis Institute (United States); R. Lynch, Infrared Institute of the Desert (United States)
- 8354 0W **Investigation of thermal effects caused by interaction of laser radiation with soft tissues** [8354-33]
M. Kastek, T. Piatkowski, H. Polakowski, A. Zajac, Military Univ. of Technology (Poland)

- 8354 0X **Human ear detection in the thermal infrared spectrum** [8354-34]
A. Abaza, West Virginia High Tech Foundation (United States); T. Bourlai, West Virginia Univ. (United States)
- 8354 0Y **Use of infrared imaging to predict the developmental stages and differences in chicken embryos exposed to different photoperiods** [8354-35]
R. A. Frederick, Tulane Univ. (United States); S.-J. Hsieh, B. G. Palomares, Texas A&M Univ. (United States)

SESSION 8 RESEARCH AND DEVELOPMENT TOPICS I

- 8354 0Z **Accurate thermal imaging of low-emissivity surfaces using approximate blackbody cavities** [8354-37]
S. F. Turner, S. F. Metcalfe, A. Mellor, J. Willmott, P. Drögmöller, Land Instruments International (United Kingdom)
- 8354 10 **Microscale thermal analysis with cooled and uncooled infrared cameras** [8354-38]
J. Morikawa, Tokyo Institute of Technology (Japan); E. Hayakawa, ai-Phase Co., Ltd. (Japan); T. Hashimoto, Tokyo Institute of Technology (Japan)

SESSION 9 RESEARCH AND DEVELOPMENT TOPICS II

- 8354 11 **On the thermal-offset in NIR hyperspectral cameras** [8354-39]
F. Parra, Univ. de Concepción (Chile) and Aeronautical Polytechnic Academy Chilean Air Force (Chile); J. E. Pezoa, P. Meza, S. N. Torres, O. Zapata, Univ. de Concepción (Chile)
- 8354 12 **Variable filter array spectrometer of VPD PbSe** [8354-40]
R. Linares-Herrero, G. Vergara, R. Gutiérrez-Álvarez, C. Fernández-Montojo, L. J. Gómez, V. Villamayor, A. Baldasano-Ramírez, M. T. Montojo, New Infrared Technologies, S.L. (Spain)
- 8354 13 **Radiance and atmosphere propagation-based method for the target range estimation** [8354-42]
H. Cho, J. Chun, KAIST (Korea, Republic of)
- 8354 14 **Spatial concentration distribution model for short-range continuous gas leakage of small amount** [8354-43]
M. Wang, L. Wang, J. Li, Y. Long, Y. Gao, Beijing Institute of Technology (China)
- 8354 15 **Gas imaging detectivity model combining leakage spot size and range** [8354-44]
J. Li, L. Wang, M. Wang, Y. Gao, W. Jin, Beijing Institute of Technology (China)

Author Index

Conference Committee

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Session Chairs

- 1 Nondestructive Testing (NDT) I
 Douglas Burleigh, La Jolla Cove Consulting (United States)
 K. Elliott Cramer, NASA Langley Research Center (United States)
 Vladimir P. Vavilov, Tomsk Polytechnic University (Russian Federation)
- 2 Nondestructive Testing (NDT) II
 Douglas Burleigh, La Jolla Cove Consulting (United States)
 K. Elliott Cramer, NASA Langley Research Center (United States)
 Vladimir P. Vavilov, Tomsk Polytechnic University (Russian Federation)
- 3 Aerospace
 Morteza Safai, The Boeing Company (United States)
 Sheng-Jen Hsieh, Texas A&M University (United States)
- 4 Buildings
 Timo T. Kauppinen, VTT Technical Research Center of Finland (Finland)
 Gregory R. Stockton, Stockton Infrared Thermographic Services, Inc.
 (United States)
- 5 Industrial Applications
 Gregory R. Stockton, Stockton Infrared Thermographic Services, Inc.
 (United States)
- 6 Security and Surveillance
 Gregory R. Stockton, Stockton Infrared Thermographic Services, Inc.
 (United States)
- 7 Biological Applications
 Morteza Safai, The Boeing Company (United States)
 Piotr Pregowski, Pregowski Infrared Services (Poland)
- 8 Research and Development Topics I
 Gary L. Orlove, FLIR Systems, Inc. (United States)
- 9 Research and Development Topics II
 Ralph B. Dinwiddie, Oak Ridge National Laboratory (United States)
 Gary L. Orlove, FLIR Systems, Inc. (United States)

Introduction

After having been in Orlando for 25 years, Thermosense has now moved to Baltimore. The change in venue has resulted in a slightly larger audience for the conference and the number of vendors in the exhibition hall was considerably larger in 2012. And since Thermosense is no longer tied to Easter, traveling will be easier.

In 2012 significant developments in Infrared imaging equipment were seen. Developments include scanners IR cameras with focal plane array (FPA) detectors as large as 1000x1000, which have improved sensitivity and faster scan rates than ever before. Prototypes of 2000x2000 FPA's were being shown at the exhibit this year.

Also, in recent years, low cost IR cameras have become available from several manufacturers. It's now possible to buy a low resolution IR camera for as little as \$3K. This can make IR technology available to more users for more applications. Unfortunately, this can also put IR cameras in the hands of untrained operators who may incorrectly collect or interpret IR data. And this can reflect poorly on the IR field.

It is a challenge for those of us who have been involved in IR for many years to prevent the use of IR cameras by operators with insufficient training or guidance.

The use of thermography for preventive maintenance (PM) and nondestructive testing (NDT) is becoming more accepted and even required. Thermography has been shown to provide valuable information which has been previously difficult or impossible to obtain. It may provide unique solutions to problems which previously had none. The demonstrated uses of thermography are numerous. The number of future applications is virtually infinite.

The Thermosense conference has played a significant role in the development of thermographic applications and equipment. It has been an important forum which annually unites researchers and practical users of thermography for a sharing of ideas and experiences.

This year's Thermosense conference includes papers from Austria, Brazil, Canada, Chile, China, Finland, France, Greece, India, Italy, Japan, Korea, Poland, Russia, Spain, and the United States, with attendees from additional countries, making it a truly international conference.

**Douglas Burleigh
Gregory R. Stockton**

